

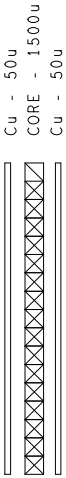
DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	FINISHED SIZE	PLATED	QTY	
A	12.0	PLATED	530	
B	31.5	PLATED	21	
C	35.43	PLATED	37	
D	40.0	PLATED	10	
E	43.31	PLATED	14	
F	51.0	PLATED	2	
G	55.0	PLATED	5	
H	59.05	PLATED	4	
I	82.68	PLATED	2	
L	40.16	NON-PLATED	2	
M	125.98	NON-PLATED	4	

TOTAL HOLES: 631

FABRICATION NOTE:

- 1:FABRICATE USING LATEST REVISION OF IPC-6012A CLASS 2 OR ABOVE
- 2:FABRICATE USING MASTER ARTWORK EVSPIN32G0602S1 R1 FOR CIRCUIT PATTERN
NO DEVIATION FROM MASTER ARTWORK ARE PERMITTED WITHOUT WRITTEN APPROVAL FROM AN AUTHORIZED STMicroelectronics REPRESENTATIVE
- 3:VENDOR MUST BE UL QUALIFIED AND BOARDS MUST BE IDENTIFIED WITH APPROPRIATE VENDOR UL IDENTIFICATION MARK, LOT OR JOB NUMBER AND PCB MATERIAL FLAMMABILITY RATING (94V-0) MINIMUM
- 4:MATERIAL: FR4 RoHS COMPLIANT MINIMUM 170 C (High Tg)
- 5:SEE "DETAIL 'A'" FOR BOARD THICKNESS, COPPER WEIGHT AND LAYER CONSTRUCTION
- 6:GREEN SOLDER MASK BOTH SIDE OF BOARD WITH LIQUID PHOTO IMAGEABLE SOLDERMASK
- 6:FINISH: HAL Lead Free
- 7:FOR SMT COMPONENTS WITH PIN PITCH OF 0.019 INCH OR MORE NO GANG RELIEF OF SOLDER MASK IS ALLOWED
- 8:SILKSCREEN TO BE WHITE, NON CONDUCTIVE, EPOXY INK OR EQUIVALENT
- 9:THIS IS NOT A CONTROLLED IMPEDANCE BOARD
- 10:DESIGNATED AREA OR INSPECTION AND TEST STAMP
- 11:ON BOTTOM PCB MUST BE IDENTIFIED MANUFACTURER LOGO AND PCB TYPE (MEANS OF MATERIAL TYPE INDICATED ON THE YELLOW CARD DOCUMENT)
- 12:VENDOR TO PROVIDE BOARD STACK-UP AND IMPEDANCE (IF REQUIRED) APPROVAL PRIOR TO BOARD FABRICATION STACK UP AND IMPEDANCE (IF REQUIRED) TO INCLUDE COPPER PLATING ON OUTER LAYERS.FAB DRAWING STACK-UP DIMENSION ARE PROVIDED FOR REFERENCE ONLY
- VENDOR TO PROVIDE BOARD FOR IMPEDANCE TEST RESULTS AND COUPON (IF REQUIRED)
- 13:TEARDROPPING OF VIAS AND PADS ALLOWED AT PAD TO TRACE INTERSECTION TO INSURE A 2MIL ANULAR RING AT THE JUNCTION
- 14:REMOVE SILKSCREEN FROM SOLDERABLE SURFACE
- 15:ALL BOARD TO BE 100% ELECTRICALLY NETLIST TESTED FOR OPENS AND ON SHORTS, APPLY TEST STAMP IN REFERENCED AREA
- 16:THIS BOARD SHALL BE FULLY COMPLIANT WITH UL796

DETAIL "A"
LAYER BUILD UP
(reference only)



(external Cu th are after plating)
estimated total thickness 1640u

Finished Hole Tolerance - All units are in Inches -			
Finish Hole Diameter	Plated Through Finish Hole Diameter	Non Plated Through Finish Hole Diameter	
0.008"-0.013"	+0.002/-FHS"	+/-0.002"	
0.014"-0.063"	+/-0.003"	+/-0.002"	
0.064"-0.156"	+/-0.004"	+/-0.003"	
0.157"-0.250"	+/-0.007"	+/-0.004"	
0.251" and up	+/-0.007"	+/-0.005"	
0.125"	Non Plated Only	+0.003/-0.000"	

REVISION DATE



APMS Group
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Drawn
M. Rigo
date
12-Feb-2024

Approved
date

Description

EVSPIN32G0602S1
DRILLING AND PROFILING

Symbol

STSPIN32G0602Q

Group

ISO
SCALE:
1 : 1
REV.
1.0

Material

Treatment and surface finishing